

Title (en)
THERMAL INTERFACE MATERIALS AND METHODS FOR PROCESSING THE SAME

Title (de)
WÄRMEZWISCHENSCHICHTMATERIALIEN UND VERFAHREN ZU IHRER VERARBEITUNG

Title (fr)
MATÉRIAUX D'INTERFACE THERMIQUE ET PROCÉDÉS POUR LEUR TRANSFORMATION

Publication
EP 2710628 A2 20140326 (EN)

Application
EP 12785480 A 20120517

Priority
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Abstract (en)
[origin: US2012292005A1] A thermal interface material is provided for use to fill a gap between surfaces in a thermal transfer system to transfer heat between the surfaces. The thermal interface material includes a base material and thermally conductive particles dispersed within the base material. The thermal interface material is conditioned under reduced pressure (e.g., prior to being placed in the gap between the surfaces, while being placed in the gap, after being placed in the gap, etc.) and, within about forty-eight hours or less of conditioning, the conditioned thermal interface material is either positioned in a container that inhibits ambient gas from contacting it (either alone or applied to the surfaces), or used to transfer heat between the surfaces. As such, the thermal interface material is substantially free of cracks following exposure to thermal cycling comprising a temperature change of at least about 100 degrees Celsius for at least about 10 cycles.

IPC 8 full level
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